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**CHANG et al.**(10) **Pub. No.: US 2022/0361321 A1**(43) **Pub. Date: Nov. 10, 2022**(54) **SENSOR LENS ASSEMBLY HAVING  
NON-REFLOW CONFIGURATION****G02B 7/00** (2006.01)**H05K 1/18** (2006.01)**H05K 1/11** (2006.01)(71) Applicant: **KINGPAK TECHNOLOGY INC.**,  
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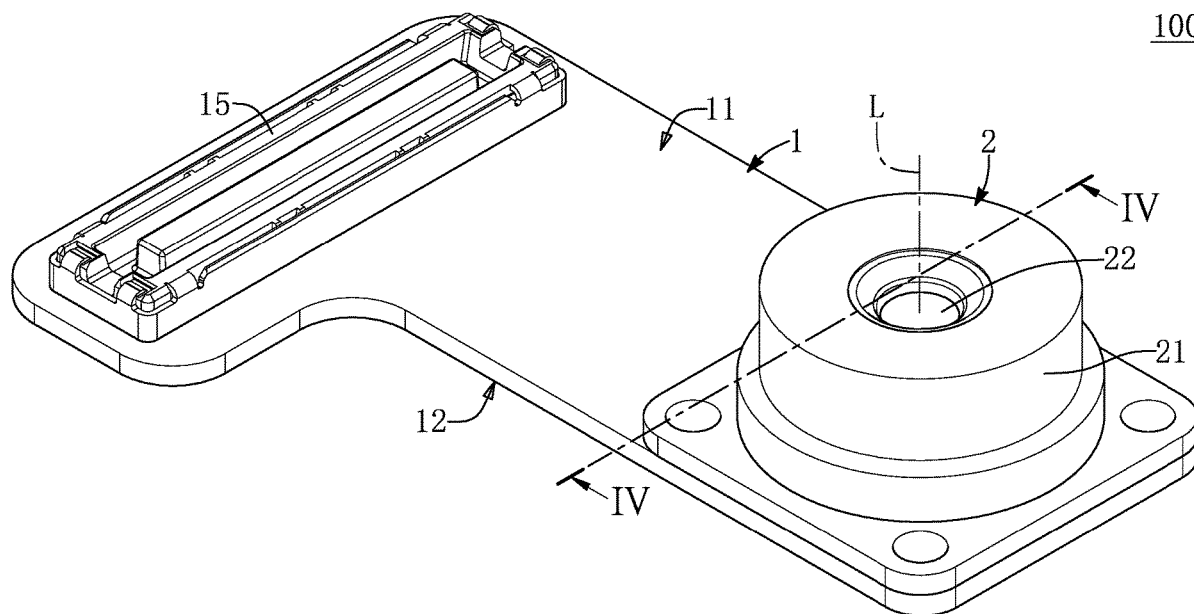
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**ABSTRACT**(22) Filed: **Jan. 11, 2022****Related U.S. Application Data**(60) Provisional application No. 63/184,622, filed on May  
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A sensor lens assembly having a non-reflow configuration is provided. The sensor lens assembly includes a circuit board, an optical module fixed to a surface of the circuit board, a sensor chip assembled to the surface of the circuit board, a plurality of wires electrically coupling the sensor chip and the circuit board, a supporting adhesive layer, a light-permeable sheet, and a top shielding layer. The circuit board has no slot recessed in the surface thereof. The supporting adhesive layer is in a ringed shape and is disposed on a top surface of the sensor chip. The light-permeable sheet is disposed on the supporting adhesive layer and faces the sensor chip. The top shielding layer is formed on an outer surface of the light-permeable sheet and has an opening that is located above a sensing region of the sensor chip.



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